

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









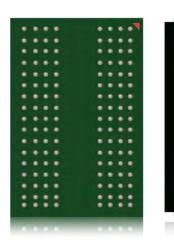
PRODUCT BRIEF | MCP

PARALLELCELL MULTI-CHIP PACKAGE (MCP)

Ultra High Density Memory Solution for Embedded Applications

Viking Technology ParallelCell Multi-Chip Package (MCP) is part of the extreme density line of DDR3 and DDR4 memory products optimized for the embedded, industrial, and military/aerospace markets. ParallelCell products achieve significantly higher memory performance and density per cubic inch than conventional memory DIMMs. These performance and density milestones will critically change the way future system hardware is designed and deployed.





BENEFITS

Very small footprint: Saves up to 85% board space vs. Standard DIMM Modules

Rugged: Soldered-down PBGA – No DIMM connector Very high memory capacity per cu. in.

Superior signal integrity

Very high memory bandwidth per cu. in.

Lower cost motherboard due to easier DDR routing



4GB LRDIMM (133.35mm x 30mm)



4GB SODIMM (67.6mm x 30mm)



4GB MINI-DIMM (82mm x 30mm)



Actual size

4GB PARALLEL CELL MCP (15mm x 20mm) A full size module in a ultra small form factor MCP.

Up to 85% Space savings Ruggedization Optimized for embedded applications Greater I/O per cu. in.

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SPEEDS		VOLTAGE	
DDR3	1333/1600/1866	DDR3	1.5V/1.35V
DDR4	2133/2400/2667	DDR4	1.2V
TEMPERATURE			
Industrial	-40°C to 85°C		
Extended	-40°C to 105°C		
Military	-55°C to 125°C		

DDR3 / DDR4 MULTI-CHIP PACKAGE

VIKING P/N	DDR TYPE	# MEMORY WORDS (M)	BUS WIDTH*	# CHANNELS	MODULE DENSITY	PACKAGE SIZE (MM)	PACKAGE HEIGHT	BALL COUNT	BALL PITCH
VPM7U1240D6B3PD1xyz	DDR3	512	40	2 (BANK A & BANK B)	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1240D6B3PF1xyz	DDR3	512	40	2 (BANK A & BANK B)	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1240D6B3PG1xyz	DDR3	512	40	2 (BANK A & BANK B)	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1272S6B3PD1xyz	DDR3	512	72	1	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1272S6B3PF1xyz	DDR3	512	72	1	4GB	15 x 20	1.9mm	321	0.8mm
VPM7U1272S6B3PG1xyz	DDR3	512	72	1	4GB	15 x 20	1.9mm	321	0.8mm
VPM9U1232D6B0PG1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1232D6B0PH1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1232D6B0PJ1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1232D6B0PK1xyz	DDR4	512	32	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PG1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PH1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PJ1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1240D6B0PK1xyz	DDR4	512	40	2	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PG1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PH1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PJ1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm
VPM9U1272S6B0PK1xyz	DDR4	512	72	1	4GB	15 x 20	1.9mm	391	0.8mm

^{*} Dual channel devices may be configured to a signal channel with 2X word width by connecting both sets of address/command/control pins.

For price and availability, please email us at sales@vikingtechnology.com.



Global Locations							
US Headquarters	Canada Office	Texas Office	India Office	Singapore Office			
2950 Red Hill Avenue Costa Mesa, CA 92626 Main: +1 714 913 2200	500 March Road Ottawa, ON K2K 0J9 Canada	1201 W. Crosby Road Carrollton, TX 75006 USA	A 3, Phase II, MEPZ-Special Economic Zone NH 45, Tambaram, Chennai-600045 India	No 2 Chai Chee Drive Singapore, 109840			

For all of our global locations, visit our website under global locations. For sales information, email us at sales@vikingtechnology.com